

# LM4060 20ppm/°C Maximum Drift High Precision Shunt Voltage Reference

## 1 Features

- Low operating current:
  - 40µA typical
- Initial accuracy: ±0.05 % (maximum)
- Temperature coefficient:
  - 6ppm/°C typical for –40°C to 125°C
- Wide operating current range up to 50mA
- No output capacitor required
- Capable of driving capacitive loads up to 4.7µF
- Output voltages options:
  - 1.25V, 1.5V, 1.6V, 1.65V, 2.048V, 2.5V, 3V, 3.3V, 4.096V, 5V
- Low output noise:
  - 10Hz to 1kHz: 26ppm<sub>rms</sub>
  - Output 1/f noise (0.1Hz to 10Hz): 9ppm<sub>P-P</sub>
- Long-term stability: 40ppm at 500 hours
- Specified temperature range –40°C to 125°C
- Small footprint 3-pin SOT–23 package
- Pin-to-pin compatible with LM4040, LM4040-N, TL4050, and LM4050-N

## 2 Applications

- [Data-acquisition systems](#)
- [Instrumentation and test equipment](#)
- [Process control](#)
- [Energy management, metering](#)
- [Precision audio](#)

## 3 Description

The LM4060 is a family of high-precision shunt voltage references. The LM4060 family offers low 20ppm/°C temperature coefficient and 0.05% high precision initial accuracy. The LM4060 design eliminates the need for an external stabilizing capacitor and provides stability with capacitive loads up to 4.7µF. The LM4060 is offered in several fixed reverse breakdown voltages: 1.25V, 1.5V, 1.6V, 1.65V, 2.048V, 2.5V, 3V, 3.3V, 4.096V, 5V. The flexible voltage options make the LM4060 a companion device for ADCs, DACs, and level shifting signal conditioning circuits.

The LM4060 supports a maximum operating current up to 50mA to support a wide range of loads. The wide load current support allows for powering of ADCs, DACs, and MCUs while providing a stable voltage reference. The LM4060 functionality is similar to a Zener diode where the cathode voltage is constant above the minimum operating current. The LM4060 can be powered from a wide input supply voltage but an external resistor is required.

The LM4060 is specified for –40°C and 125°C, which enables operation across various industrial applications.

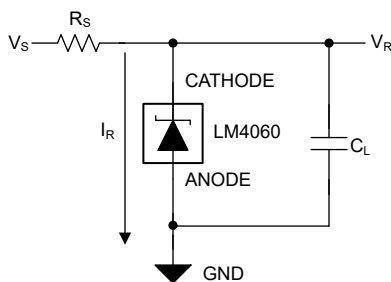
### Package Information

PART NUMBER	PACKAGE <sup>(1)</sup>	PACKAGE SIZE <sup>(2)</sup>
LM4060	DBZ (SOT-23, 3)	2.92mm × 2.37mm

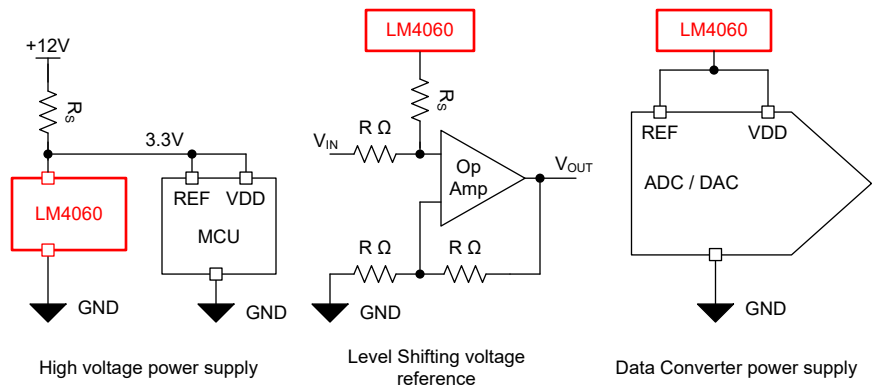
(1) For more information, see [Section 12](#).

(2) The package size (length × width) is a nominal value and includes pins, where applicable.

Connection Diagram



Typical Application Use Cases



LM4060 Use Case



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## 4 Device Comparison Table

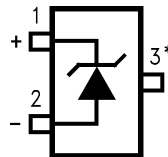
The LM4060 has multiple voltage options available. Use [Table 4-1](#) as the part number decoding table for all devices. For devices marked preview, contact TI sales representatives or on TI's [E2E](#) forum for details and availability of other options.

**Table 4-1. Device Comparison Table**

ORDERABLE PART NAME	V <sub>R</sub>
LM4060A12EDBZR	1.25V
LM4060A15EDBZR <sup>(1)</sup>	1.5V
LM4060A16EDBZR <sup>(1)</sup>	1.6V
LM4060A165EDBZR <sup>(1)</sup>	1.65V
LM4060A18EDBZR <sup>(1)</sup>	1.8V
LM4060A20EDBZR	2.048V
LM4060A25EDBZR	2.5V
LM4060A30EDBZR	3.0V
LM4060A33EDBZR	3.3V
LM4060A41EDBZR <sup>(1)</sup>	4.096V
LM4060A50EDBZR	5.0V

(1) Preview Information (not Production Data).

## 5 Pin Configuration and Functions



\*This pin must be left floating or connected to pin 2.

**Figure 5-1. DBZ Package  
3-Pin SOT-23  
Top View**

**Table 5-1. Pin Functions**

PIN		TYPE <sup>(1)</sup>	DESCRIPTION
NAME	NO.		
Cathode	1	I/O	Shunt current and input voltage
Anode	2	O	Common pin, normally connected to ground
DNC	3	—	This pin must be left floating or connected to pin 2.

(1) I = input, O = output

## 6 Specifications

### 6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
$I_R$	Reverse Current		55	mA
$T_J$	Maximum Junction Temperature		150	C
$T_{stg}$	Storage Temperature	-65	150	C

- (1) Operation outside the Absolute Maximum Ratings may cause permanent device damage. Absolute Maximum Ratings do not imply functional operation of the device at these or any other conditions beyond those listed under Recommended Operating Conditions. If used outside the Recommended Operating Conditions but within the Absolute Maximum Ratings, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.

### 6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>	±2000	V
		Charged device model (CDM), per ANSI/ESDA/JEDEC JS-002 <sup>(2)</sup>	±750	

- (1) JEDEC document JEP155 states that 500V HBM allows safe manufacturing with a standard ESD control process  
(2) JEDEC document JEP157 states that 250V CDM allows safe manufacturing with a standard ESD control process

### 6.3 Recommended Operating Conditions

conditions apply over the operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
$I_R$	Continuous Cathode Current Range	$I_{RMIN}$	50	mA
$T_J$	Junction Temperature	-40	125	C

### 6.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		LM4060	UNIT
		DBZ (SOT-23)	
		3 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	229.8	C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	107.7	C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	99.4	C/W
$\Psi_{JT}$	Junction-to-top characterization resistance	16.5	C/W
$\Psi_{JB}$	Junction-to-board characterization resistance	98.6	C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application note.

## 6.5 Electrical Characteristics

over recommended operating conditions,  $T_J = 25^\circ\text{C}$  (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
$V_R$	Reverse breakdown voltage Accuracy	$I_R = 100\mu\text{A}$		-0.05		0.05	%
$V_R$	Output voltage temperature coefficient <sup>(1)</sup>	$I_R = 100\mu\text{A}$	$T_J = -40^\circ\text{C}$ to $125^\circ\text{C}$		6	20	ppm/ $^\circ\text{C}$
$I_{R\text{MIN}}$	Minimum cathode current		$T_J = -40^\circ\text{C}$ to $125^\circ\text{C}$		35	50	$\mu\text{A}$
$\Delta V_R/\Delta I_R$	Reverse Breakdown Voltage Change with Operating Current Change	$I_{R\text{MIN}} < I_R < 50\text{mA}$	$T_J = -40^\circ\text{C}$ to $125^\circ\text{C}$			50	ppm/mA
$Z_R$	Reverse Dynamic Impedance <sup>(2)</sup>	$I_R = 1\text{mA}$ , $F = 120\text{Hz}$ , $I_{AC} = 0.1 I_R$			0.55	1.5	$\Omega$
$e_{\text{np-p}}$	Low frequency noise	$I_R = 100\mu\text{A}$ , $0.1\text{Hz} \leq f \leq 10\text{Hz}$			9		$\mu\text{V}_{\text{p-p}}/\text{V}$
$e_N$	Wideband Noise	$I_R = 100\mu\text{A}$ , $10\text{Hz} \leq f \leq 10\text{kHz}$			27		ppm <sub>rms</sub>
$V_{\text{HYST}}$	Thermal Hysteresis	$V_R = 3.3\text{V}$	$T_A = 25^\circ\text{C}$ , $-40^\circ\text{C}$ , $125^\circ\text{C}$ , $25^\circ\text{C}$ (cycle 1)		130		ppm
$V_{\text{HYST}}$	Thermal Hysteresis	$V_R = 3.3\text{V}$	$T_A = 25^\circ\text{C}$ , $-40^\circ\text{C}$ , $125^\circ\text{C}$ , $25^\circ\text{C}$ (cycle 2)		20		ppm
$C_L$	Stable output capacitor range		$T_J = -40^\circ\text{C}$ to $125^\circ\text{C}$			4.7	$\mu\text{F}$
$t_{\text{ST}}$	Settling Time	$I_R = 100\mu\text{A}$ , $C_L = 0\mu\text{F}$ , 99% of $V_R$			2000		$\mu\text{s}$
$t_{\text{ST}}$	Settling Time	$I_R = 1\text{mA}$ , $C_L = 1\mu\text{F}$ , 99% of $V_R$			6		mS

- (1) The temperature coefficient parameter for  $V_R$  is calculated using the box method which is the difference between the maximum and minimum values obtained over the rated temperature range. For more details on  $V_R$  and average temperature coefficient, see [Parameter Measurement Information](#).
- (2) The dynamic impedance is defined by  $|Z_R| = \Delta V_R/\Delta I_R$ . For more details on  $|Z_R|$  and how it relates to  $V_R$ , see [Section 7](#)

## 6.6 Typical Characteristics

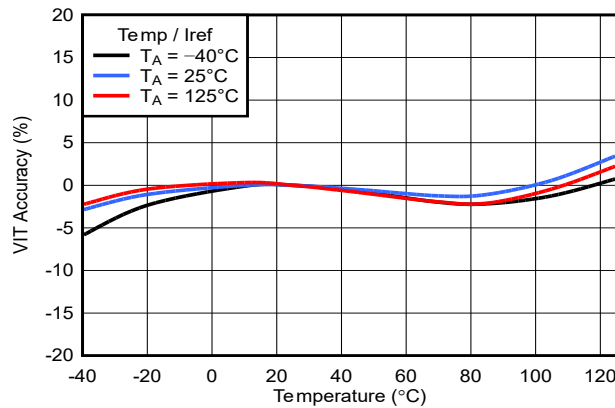


Figure 6-1. Temperature Drift

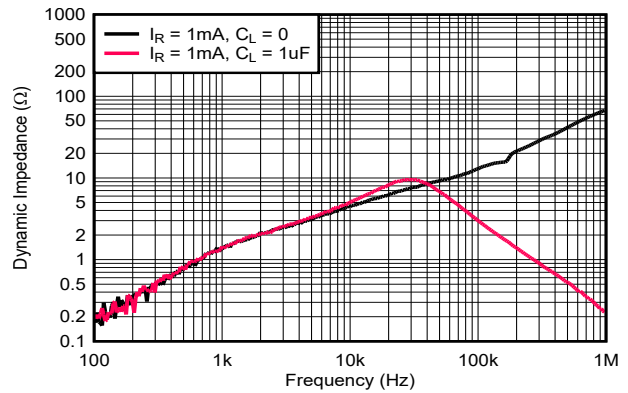


Figure 6-2. Output Impedance vs Frequency,  $V_R = 1.25V$

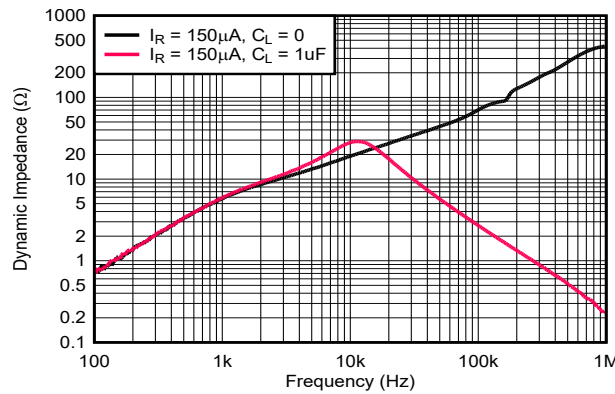


Figure 6-3. Output Impedance vs Frequency,  $V_R = 1.25V$

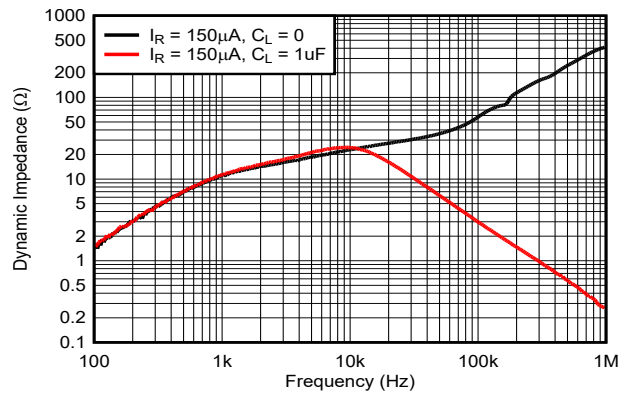


Figure 6-4. Output Impedance vs Frequency,  $V_R = 3.3V$

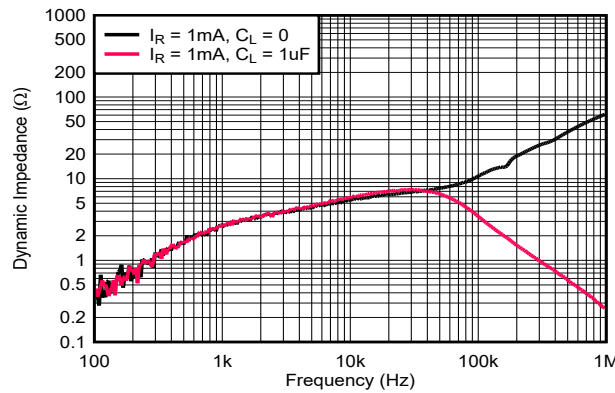


Figure 6-5. Output Impedance vs Frequency,  $V_R = 3.3V$

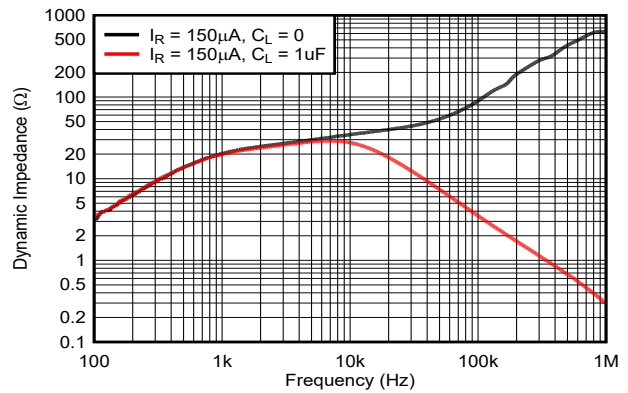
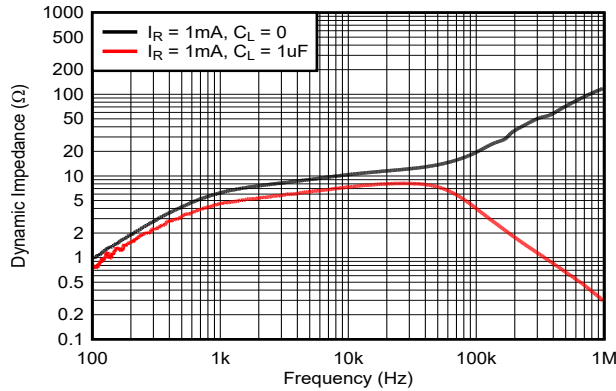
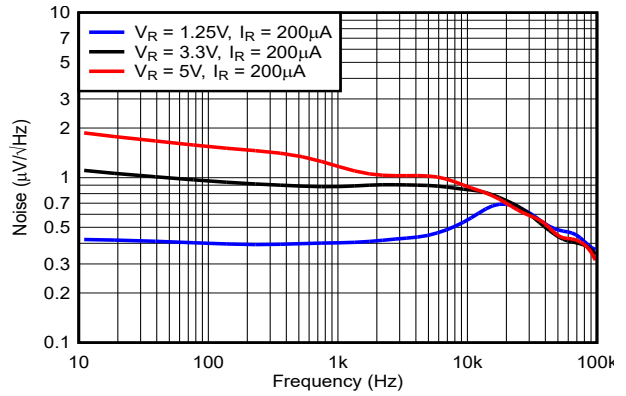


Figure 6-6. Output Impedance vs Frequency,  $V_R = 5V$

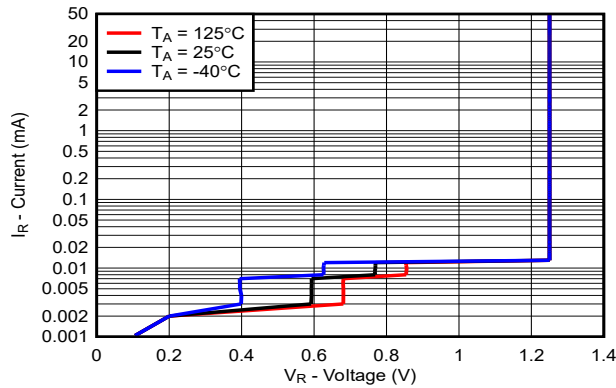
## 6.6 Typical Characteristics (continued)



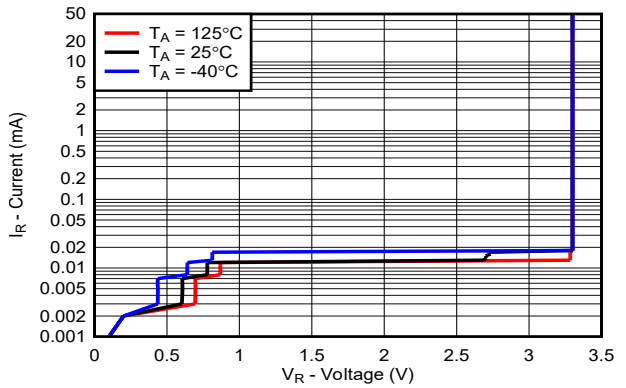
**Figure 6-7. Output Impedance vs Frequency,  $V_R = 5V$**



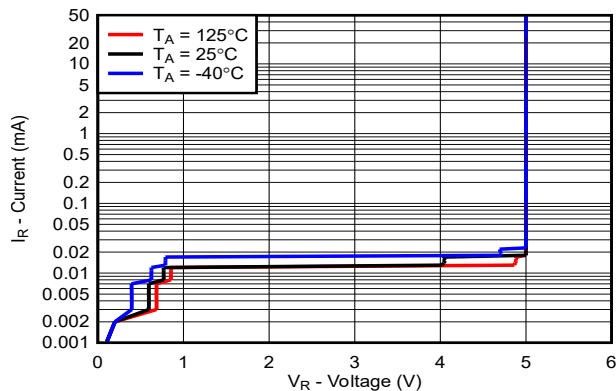
**Figure 6-8. Noise Spectral Density**



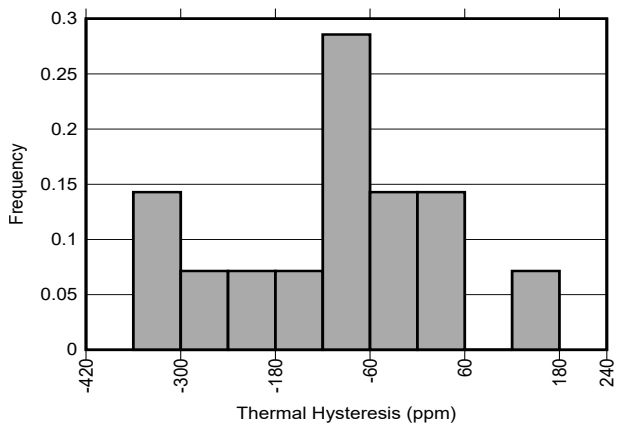
**Figure 6-9. Minimum Operating Voltage,  $V_R = 1.25V$**



**Figure 6-10. Minimum Operating Voltage,  $V_R = 3.3V$**

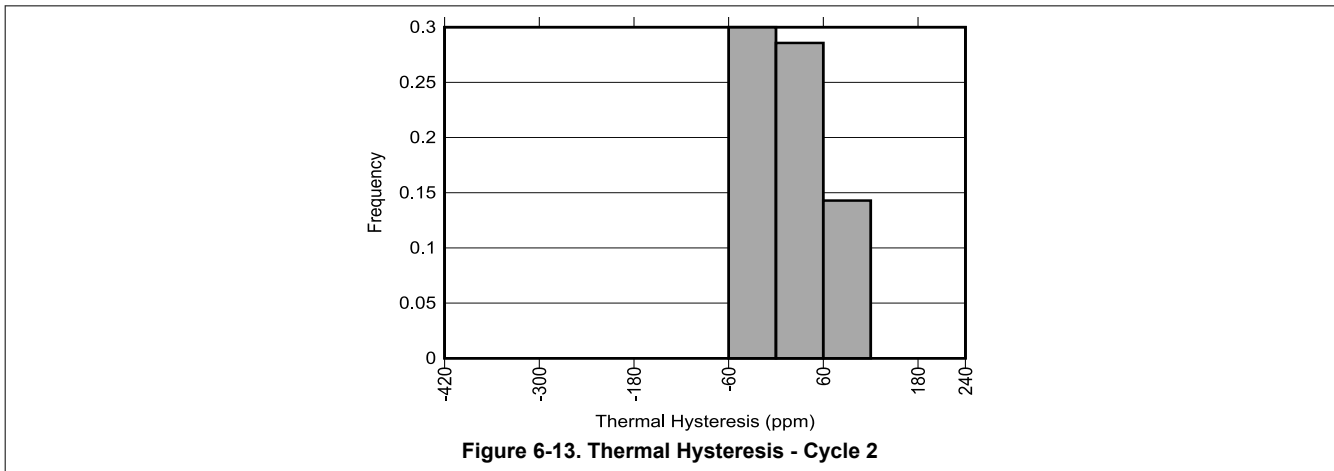


**Figure 6-11. Minimum Operating Voltage,  $V_R = 5V$**



**Figure 6-12. Thermal Hysteresis - Cycle 1**

### 6.6 Typical Characteristics (continued)

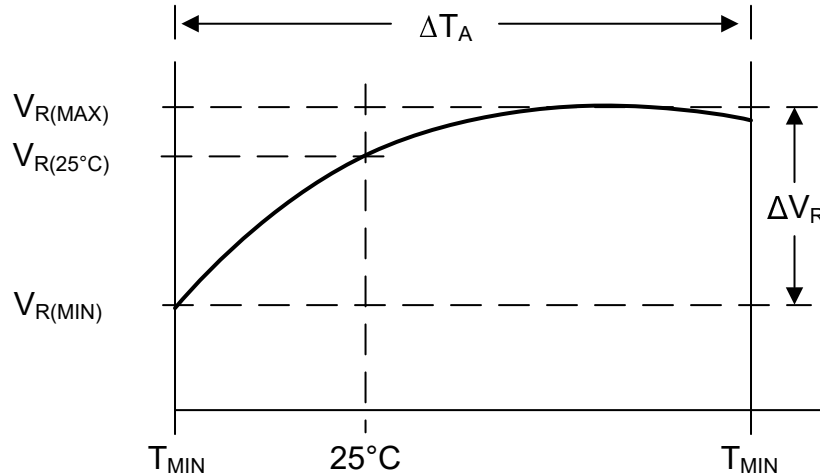


## 7 Parameter Measurement Information

### 7.1 Temperature Coefficient

The LM4060 temperature coefficient is calculated using the box method. The box method temperature coefficient of  $V_R$  is defined in [Figure 7-1](#). The box method temperature coefficient is an average of the full operating temperature range and therefore any subsection of the rated operating temperature range can yield a value that is greater or less than the average. For more details on temperature coefficient, refer to the [Voltage Reference Selection Basics white paper](#).

$$TC_{\text{BOX}} = 10^6 \left( \frac{V_{R(\text{MAX})} - V_{R(\text{MIN})}}{V_{R(25^\circ\text{C})}} \right) \left( \frac{1}{T_{\text{MAX}} - T_{\text{MIN}}} \right) \quad (1)$$

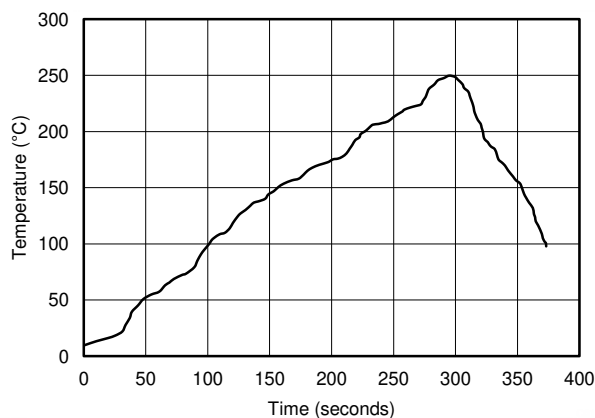


**Figure 7-1. Temperature Coefficient**

## 7.2 Solder Heat Shift

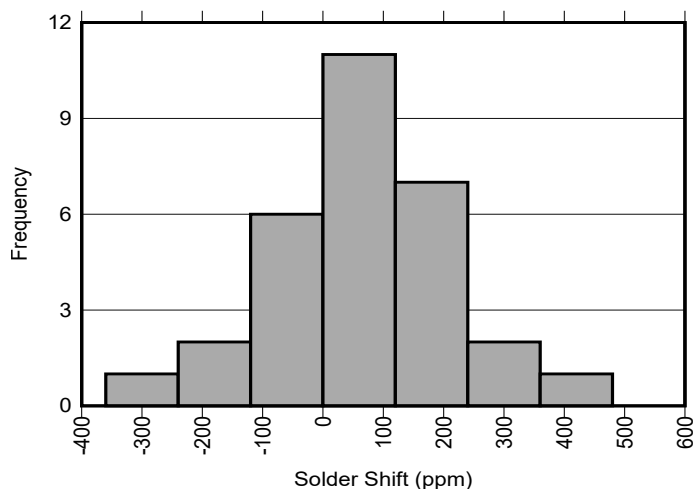
The materials used in the manufacturing of the LM4060 have differing coefficients of thermal expansion, resulting in stress on the device die when the part is heated. Mechanical and thermal stress on the device die can cause the output voltages to shift, degrading the initial accuracy specifications of the product. Reflow soldering is a common cause of this error.

To illustrate this effect, a total of 32 devices were soldered on one printed circuit board using lead-free solder paste and the paste manufacturer suggested reflow profile. [Figure 7-2](#) shows the reflow profile. The printed circuit board is comprised of FR4 material. The board thickness is 1.66mm and the area is 174mm × 135mm.



**Figure 7-2. Reflow Profile**

The reference output voltage is measured before and after the reflow process; [Figure 7-3](#) shows the typical shift. Although all tested units exhibit very low shifts (< 0.04%), higher shifts are also possible depending on the size, thickness, and material of the printed circuit board (PCB). An important note is that the histograms display the typical shift for exposure to a single reflow profile. Exposure to multiple reflows, as is common on PCBs with surface-mount components on both sides, causes additional shifts in the output bias voltage. If the PCB is exposed to multiple reflows, the device must be soldered in the last pass to minimize the exposure to thermal stress.



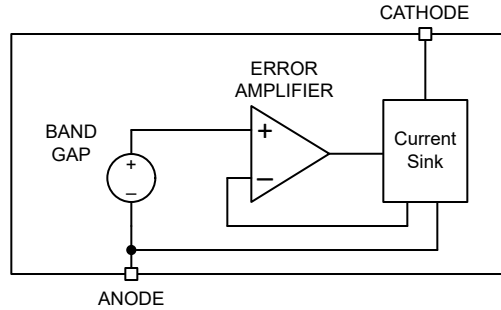
**Figure 7-3. Solder Heat Shift Distribution,  $V_{REF}$  (%)**

## 8 Detailed Description

### 8.1 Overview

The LM4060 is a family of high-precision shunt voltage references. The LM4060 family offers low 20ppm/°C temperature coefficient and 0.05% high precision initial accuracy. The LM4060 design eliminates the need for an external stabilizing capacitor and provides stability with capacitive loads up to 4.7μF.

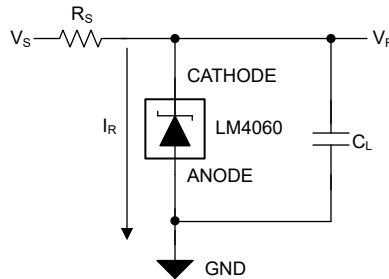
### 8.2 Functional Block Diagram



### 8.3 Feature Description

#### 8.3.1 Input Current ( $I_R$ )

In a conventional shunt regulator application (Figure 8-1), an external series resistor ( $R_S$ ) is connected between the supply voltage and the LM4060.  $R_S$  determines the current that flows through the load ( $I_L$ ) and the LM4060 ( $I_R$ ). Since load current and supply voltage varies,  $R_S$  has to be small enough to supply at least the maximum  $I_{RMIN}$  (spec. table) to the LM4060 even when the supply voltage is at the minimum and the load current is at the maximum value. When the supply voltage is at the maximum and  $I_L$  is at the minimum,  $R_S$  has to be large enough so that the current flowing through the LM4060 is less than 50mA.



**Figure 8-1. LM4060 Typical Diagram**

$R_S$  is determined by the supply voltage, ( $V_S$ ), the load and operating current, ( $I_L$  and  $I_R$ ), and the LM4060 reverse breakdown voltage,  $V_R$ .

$$R_S = \frac{V_S - V_R}{I_L + I_R} \quad (2)$$

### 8.4 Device Functional Modes

The LM4060 operates in closed loop due to the fact that the feedback is internal to the device. Additionally, the output voltage cannot be adjusted for the same reason. The output voltage is regulated in a closed loop, provided the  $R_S$  (see Figure 8-1) resistor is sized to deliver the current to the cathode within the limits specified for operation.

## 9 Application and Implementation

### Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

### 9.1 Application Information

The LM4060 shunt voltage reference with high accuracy and high sink current capabilities is suitable reference for multiple applications. The device can be used as a precision high accuracy low noise voltage reference for data converters or level shifting circuits for signal chains. With the LM4060 50mA capabilities, the device can be the voltage reference and the power supply to sensor or data converter instead of traditional LDO or DC/DC based power supply. As a shunt voltage reference, the LM4060 can be powered from any voltage rail greater than  $V_R$  with proper resistor sizing including 12V supply rails.

### 9.2 Typical Application

The following sections describe in detail how to properly use this device. As this device has many applications and setups, there are many situations that this data sheet cannot characterize in detail and vary from these applications depending on the requirements of the final application.

#### 9.2.1 Design: LM4060 Precision Power Supply and Voltage Reference

The LM4060 combination of high-precision with high current sink can be the power supply and voltage reference to a MCU. In [Figure 9-1](#), the device is able to support the load current required by both the MCU VDD pin and REF pin. The main design consideration is the  $R_S$  resistor that needs to be sized to reduce current draw but supply the load under all conditions.

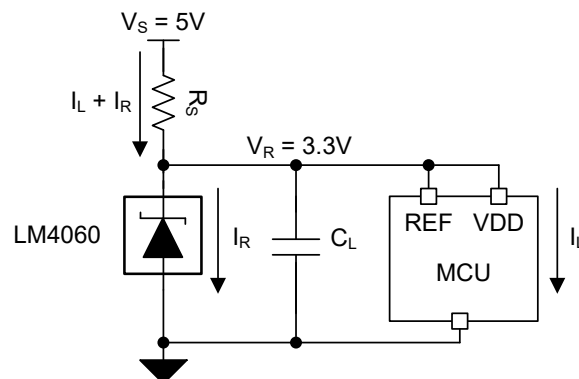


Figure 9-1. LM4060 Voltage Reference With MCU Load

#### 9.2.1.1 Design Requirements

For this design the goal is to design  $R_S$  to minimize current consumption and function worst case conditions. Use the parameters listed in [Table 9-1](#) as the input parameters.

Table 9-1. Design Parameters

DESIGN PARAMETER	VALUE
Input voltage range	4.8V to 5.2V
Input voltage typical	5V
Output voltage	3.3V
Minimum cathode current	60 $\mu$ A
Typical MCU VDD current	12mA

**Table 9-1. Design Parameters (continued)**

DESIGN PARAMETER	VALUE
Maximum MCU VDD current	20mA
Typical MCU REF current	130µA
Maximum MCU REF current	150µA

**9.2.1.2 Detailed Design Procedure**

$R_S$  sets the cathode current of the shunt reference and is calculated using Equation 3. The resistor  $R_S$  must be selected such that current  $I_R$  remains in the operational region of the part for the entire  $V_S$  range and load current range  $I_L$ .

$$R_S = \frac{V_S - V_R}{I_L + I_R} \tag{3}$$

The two extremes to consider are  $V_S$  at the minimum, and the load at the maximum, where  $R_S$  must be small enough for  $I_R$  to remain above  $I_{RMIN}$ . For this design, design  $I_R$  with a small margin of current for a total of 0.1mA. This design makes the maximum  $R_S$  required to maintain operation at the worst case conditions to be 74Ω.

$$R_{SMAX} = \frac{V_{SMIN} - V_R}{I_{LMAX} + I_R} = \frac{4.8V - 3.3V}{20mA + 0.15mA + 0.1mA} = 74\Omega \tag{4}$$

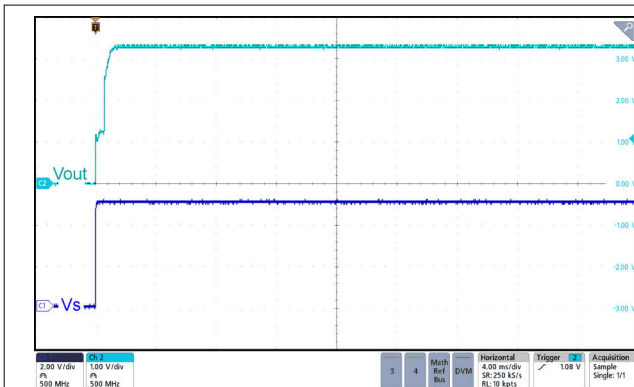
The other extreme is  $V_S$  at the maximum, and the load at the minimum, where  $R_S$  must be large enough to maintain  $I_R < I_{RMAX}$ . For this design, the assumption is that the load is off. The calculated  $I_{RMAX}$  is 25.6mA, which is less than the maximum the device can support.

$$I_{RMAX} = \frac{V_{SMAX} - V_R}{R_S} - I_{LMIN} = \frac{5.2V - 3.3V}{74\Omega} = 25.6mA \tag{5}$$

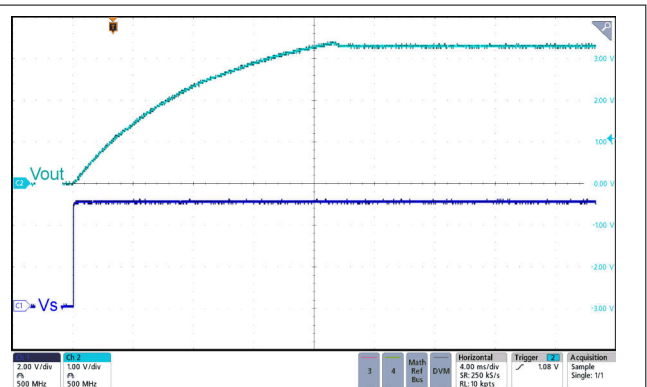
The same equation above is used to find out the typical current the device sinks.

$$I_R = \frac{V_S - V_R}{R_S} - I_L = \frac{5V - 3.3V}{74\Omega} - 12mA - 0.13mA = 10.8mA \tag{6}$$

**9.2.1.3 Application Curves**



**Figure 9-2. LM4060 Start-Up With  $C_L =$  Open,  $I_R = 0mA$ , Variant: LM4060A33EDBZR**



**Figure 9-3. LM4060 Start-Up With  $C_L = 1\mu F$ ,  $I_R = 0mA$ , Variant: LM4060A33EDBZR**

### 9.3 Power Supply Recommendations

Noise on the power supply input to  $R_S$  can affect output noise performance. Noise performance can be reduced by using an optional bypass capacitor at the input side of  $R_S$  and Ground. TI recommends a 0.1 $\mu$ F ceramic capacitor or higher.

#### 9.3.1 Power Dissipation and Device Operation

The permissible power dissipation for any package is a measure of the capability of the device to pass heat from the power source, the junctions of the IC, to the ultimate heat sink, the ambient environment. Thus, the power dissipation is dependent on the ambient temperature and the thermal resistance across the various interfaces between the die junction and ambient air.

Use [Equation 7](#) to calculate the maximum continuous allowable power dissipation for the device in a given package:

$$P_{D-MAX} = ((T_{J-MAX} - T_A) / R_{\theta JA}) \quad (7)$$

[Equation 8](#) calculates the actual power being dissipated in the device:

$$P_D = V_R \times I_R \quad (8)$$

[Equation 7](#) and [Equation 8](#) establish the relationship between the maximum power dissipation allowed due to thermal consideration and the continuous current capability of the device. Use these two equations to determine the optimum operating conditions for the device in the application.

In applications where lower power dissipation ( $P_D$ ) or excellent package thermal resistance ( $R_{\theta JA}$ ) is present, the maximum ambient temperature ( $T_{A-MAX}$ ) can be increased.

In applications where high power dissipation or poor package thermal resistance is present, the maximum ambient temperature ( $T_{A-MAX}$ ) have to be derated.  $T_{A-MAX}$  is dependent on the maximum operating junction temperature ( $T_{J-MAX-OP} = 125^\circ\text{C}$ ), the maximum allowable power dissipation in the device package in the application ( $P_{D-MAX}$ ), and the junction-to ambient thermal resistance of the part and package in the application ( $R_{\theta JA}$ ), as given by [Equation 9](#):

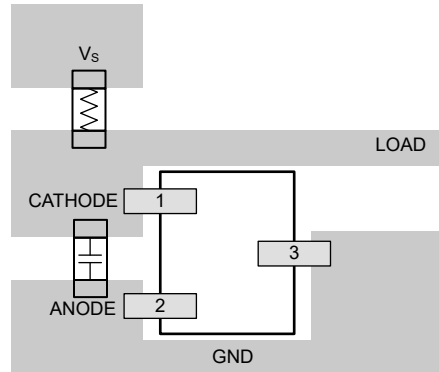
$$T_{A-MAX} = (T_{J-MAX-OP} - (R_{\theta JA} \times P_{D-MAX})) \quad (9)$$

## 9.4 Layout

### 9.4.1 Layout Guidelines

Place  $R_S$  as close to the cathode as possible. Place capacitor  $C_L$  as close to the cathode as possible.

### 9.4.2 Layout Example



**Figure 9-4. Layout Recommendation**

## 10 Device and Documentation Support

### 10.1 Third-Party Products Disclaimer

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### 10.2 Documentation Support

#### 10.2.1 Related Documentation

Texas Instruments, [Voltage Reference Selection Basics white paper](#)

### 10.3 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](#). Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 10.4 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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### 10.5 Trademarks

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### 10.6 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 10.7 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

## 11 Revision History

DATE	REVISION	NOTES
November 2025	*	Initial Release

## 12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">LM4060A12EDBZR</a>	Active	Production	SOT-23 (DBZ)   3	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	1P25C
<a href="#">LM4060A25EDBZR</a>	Active	Production	SOT-23 (DBZ)   3	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2P5XC
<a href="#">LM4060A30EDBZR</a>	Active	Production	SOT-23 (DBZ)   3	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	3P0XC
<a href="#">LM4060A33EDBZR</a>	Active	Production	SOT-23 (DBZ)   3	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	3P3XC
<a href="#">LM4060A50EDBZR</a>	Active	Production	SOT-23 (DBZ)   3	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	5P0XC

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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**OTHER QUALIFIED VERSIONS OF LM4060 :**

- Automotive : [LM4060-Q1](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

## TAPE AND REEL INFORMATION



### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM4060A12EDBZR	SOT-23	DBZ	3	3000	180.0	8.4	2.9	3.35	1.35	4.0	8.0	Q3
LM4060A25EDBZR	SOT-23	DBZ	3	3000	180.0	8.4	2.9	3.35	1.35	4.0	8.0	Q3
LM4060A33EDBZR	SOT-23	DBZ	3	3000	180.0	8.4	2.9	3.35	1.35	4.0	8.0	Q3
LM4060A50EDBZR	SOT-23	DBZ	3	3000	180.0	8.4	2.9	3.35	1.35	4.0	8.0	Q3

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM4060A12EDBZR	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4060A25EDBZR	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4060A33EDBZR	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4060A50EDBZR	SOT-23	DBZ	3	3000	210.0	185.0	35.0

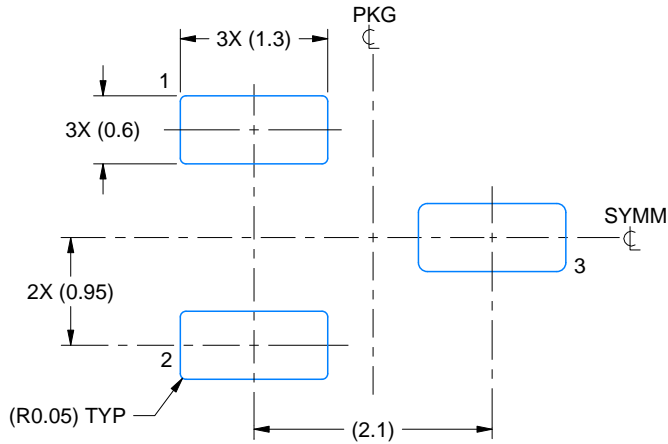


# EXAMPLE BOARD LAYOUT

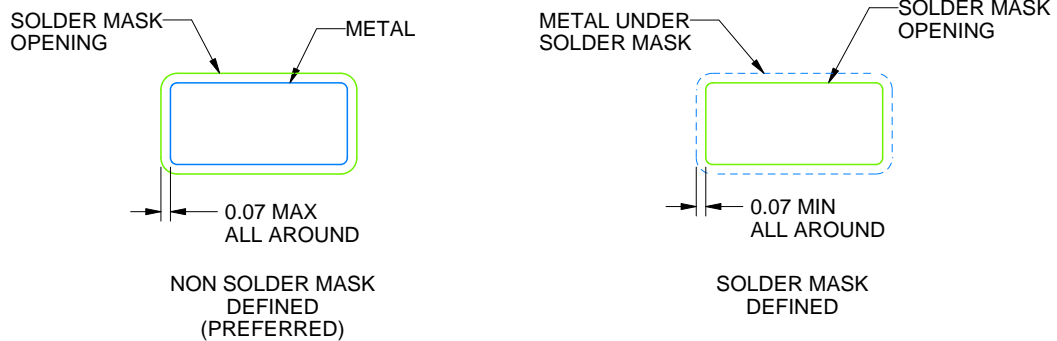
DBZ0003A

SOT-23 - 1.12 mm max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE  
SCALE:15X



SOLDER MASK DETAILS

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NOTES: (continued)

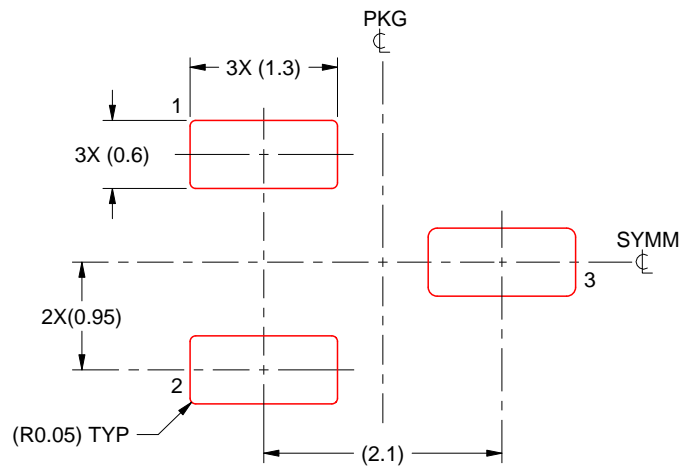
- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DBZ0003A

SOT-23 - 1.12 mm max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE  
BASED ON 0.125 THICK STENCIL  
SCALE:15X

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NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

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